



Material Content Data Sheet



Sales Product Name				IPD90N06S4L-05		Issued		24. January 2018	
MA#				MA001040324					
Package				PG-TO252-3-11		Weight*		392.07 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	3.393	0.87	0.87	8655	8655	
leadframe	non noble metal	iron	7439-89-6	0.140	0.04		357		
	inorganic material	phosphorus	7723-14-0	0.042	0.01		107		
	non noble metal	copper	7440-50-8	139.706	35.63	35.68	356324	356788	
wire	non noble metal	aluminium	7429-90-5	4.547	1.16	1.16	11596	11596	
encapsulation	organic material	carbon black	1333-86-4	1.428	0.36		3643		
	plastics	epoxy resin	-	24.999	6.38		63760		
	inorganic material	silicondioxide	60676-86-0	116.422	29.69	36.43	296939	364342	
leadfinish	non noble metal	tin	7440-31-5	3.740	0.95	0.95	9539	9539	
plating	non noble metal	nickel	7440-02-0	0.091	0.02		232		
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.02	1	233	
solder	noble metal	silver	7440-22-4	0.074	0.02		188		
	non noble metal	tin	7440-31-5	0.059	0.02		151		
	non noble metal	lead	7439-92-1	2.822	0.72	0.76	7199	7538	
heatspreader	inorganic material	phosphorus	7723-14-0	0.028	0.01		72		
	non noble metal	iron	7439-89-6	0.095	0.02		241		
	non noble metal	copper	7440-50-8	94.488	24.10	24.13	240996	241309	
*deviation	< 10%					Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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